PMP9419_BOM

PIVIP9419_BOIVI							Toler			
Commont	Description	Decimator	Contraint	LibRef	Manufactur	Value	ance		TampCa	Quant
Comment	Description	Designator	Footprint		er		_%	Value2	TempCo	ity
Suggest using a net name here	Terminal, Turret, TH, Double	+15V, -15V, GN	Test	1502-2	Keystone	Double				7
ODMOANDZALIAZAKA OAL	CAP, CERM, 0.47uF, 50V, +/- 10%, X7R, 1206	04	4000	CDM04MD74LI474KA04L	MuRata	0.475	40	50\ <i>I</i>	VZD	
GRM31MR71H474KA01L	CAP, CERM, 0.047uF, 50V, +/-	C1	1206	GRM31MR71H474KA01L	MuKala	0.47uF	10	50V	X7R	1
GRM21BR71H473KA01L	10%, X7R, 0805	C2	0805_HV	GRM21BR71H473KA01L	MuRata	0.047uF	10	50V	X7R	1
	CAP, CERM, 0.1uF, 16V, +/-	OZ.	0003_110	GRINZ I BIRT I I I I I SIRAGIE	artata	0.047 di	10	30 V	XIIX	 '
GRM188R71C104KA01D	10%, X7R, 0603	C3, C6	0603	GRM188R71C104KA01D	MuRata	0.1uF	10	16V	X7R	2
	CAP, CERM, 0.01uF, 16V, +/-	,								
GRM188R71C103KA01D	10%, X7R, 0603	C4, C7	0603	GRM188R71C103KA01D	MuRata	0.01uF	10	16V	X7R	2
	CAP, CERM, 3300pF, 50V, +/-									
GRM188R71H332KA01D	10%, X7R, 0603	C5	0603	GRM188R71H332KA01D	MuRata	3300pF	10	50V	X7R	1
	CAP, CERM, 10uF, 16V, +/-10%,									
GRM21BR61C106KE15L	X5R, 0805	C8, C9	0805_HV	GRM21BR61C106KE15L	MuRata	10uF	10	16V	X5R	2
GRM21BR61E475KA12L	CAP, CERM, 4.7uF, 25V, +/- 10%, X5R, 0805	040 044	0005 111/	ODMO4DD04E 475KA 40k	MuRata	4.7	40	05)/	VED	
	CAP, CERM, 10uF, 10V, +/-10%,	C10, C11	0805_HV	GRM21BR61E475KA12L	MuKala	4.7uF	10	25V	X5R	2
GRM21BR71A106KE51L	X7R, 0805	C13	0805_HV	GRM21BR71A106KE51L	MuRata	10uF	10	10V	X7R	1 1
	CAP, CERM, 1000pF, 2000V, +/-	013	0003_110	GRIVIZ I BIRT I A TOURLE JIL		Tour	10	10 V	X/IX	 '
C1210C102KGRACTU	10%, X7R, 1210	C14	1210	C1210C102KGRACTU	Kemet	1000pF	10	2000V	X7R	1 1
	CAP, CERM, 1uF, 16V, +/-10%,	_								
GRM188R71C105KA12D	X7R, 0603	C16	0603	GRM188R71C105KA12D	MuRata	1uF	10	16V	X7R	1
	Diode, Schottky, 45V, 0.1A, SOD-									
SDM10U45-7-F	523	D1	SOD-523	SDM10U45-7-F	Diodes Inc.	0.58V				1
	Diode, Schottky, 100V, 1A,				District					
DFLS1100-7	PowerDI123	D2, D3, D5	powerDI123	DFLS1100-7	Diodes Inc.	100V		0.77V		3
MDD0500LT4C	Diode, Schottky, 20V, 0.5A, SOD- 123		COD 400	MDD0500LT4C	Semiconduc tor			0.005\/		
MBR0520LT1G	Header 2, wurth, P/N 691 214	D8	SOD-123	MBR0520LT1G	101	20V	<u> </u>	0.385V		1
Vin	110 002, pitch 3.50mm	P1, P4	CON2-1	Header 2	Wurth					2
	Header 3, wurth, P/N 691 214	1 1,1 7	00112 1	Floader 2						
V_15V	110 003, pitch 3.50mm	P2	CON3-1	Header 3	Wurth					1
	Header 2, wurth, P/N 691 214									
V_5V	110 002, pitch 3.50mm	P3	CON2-1	Header 2	Wurth					1
CRCW0603124KFKEA	RES, 124k ohm, 1%, 0.1W, 0603	R1	0603	CRCW0603124KFKEA	Vishay-Dale	124k	1	0.1W	100 ppm/C	1
	RES, 10.0k ohm, 1%, 0.1W,	DO	0000	000000000000000000000000000000000000000	Viohov Dala	DAID		0.4144	400 10	_
CRCW060310K0FKEA	0603	R2	0603	CRCW060310K0FKEA	Vishay-Dale	DNA	1	0.1W	100 ppm/C	1
CRCW0603249KFKEA	RES, 249k ohm, 1%, 0.1W, 0603	P3	0603	CRCW0603249KFKEA	Vishay-Dale	249k	1	0.1W	100 ppm/C	
CNCWU0U3Z49NFNEA	1125, 245K OHHI, 176, 0.177, 0003	NO	0003	CNGWU0U3249NFNEA	violitay-Dale	249K	Į l	U. 1 VV	100 ppm/C	1

	RES, 49.9k ohm, 1%, 0.1W,									
CRCW060349K9FKEA	0603	R4	0603	CRCW060349K9FKEA	Vishay-Dale	49.9k	1	0.1W	100 ppm/C	1
	RES, 150k ohm, 0.1%, 0.1W,				Yageo					
RT0603BRD07150KL	0603	R5	0603	RT0603BRD07150KL	America	150k	0.1	0.1W	25 ppm/C	1
RT0603BRD0720KL	RES, 20.0k ohm, 0.1%, 0.1W, 0603	R6	0603	RT0603BRD0720KL	Yageo America	20.0k	0.1	0.1W	25 ppm/C	1
CRCW08052K00FKEA	RES, 2.00k ohm, 1%, 0.125W, 0805	R7, R8, R10	0805_HV	CRCW08052K00FKEA	Vishay-Dale	2.00k	1	0.125W	100 ppm/C	3
CRCW06031K00FKEA	RES, 1.00k ohm, 1%, 0.1W, 0603	R16	0603	CRCW06031K00FKEA	Vishay-Dale	1.00k	1	0.1W	100 ppm/C	1
CRCW060330K1FKEA	RES, 30.1k ohm, 1%, 0.1W, 0603	R17	0603	CRCW060330K1FKEA	Vishay-Dale	30.1k	1	0.1W	100 ppm/C	1
5000	Test Point, TH, Miniature, Red	SW	Test	5000	Keystone	Red				1
750342206		T1	ER11.5	Wurth '750342206	Wurth					1
LM5017MR/NOPB	100V 600mA COT Syn Buck Regulator	U1	SO PowerPAD	LM5017MR/NOPB	Texasd Instruments					1

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